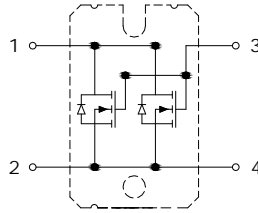


PRELIMINARY DATASHEET
**900V/ 2x31A N-Channel CoolMOS™ in Parallel
 In SOT227 Package**

- Extreme dv/dt rated
- High peak current capability
- Low gate charge
- Pb-free lead finish; RoHS compliant


MAXIMUM RATINGS, $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Units
Drain-Source voltage	V_{DS}	900V	V
Gate-Source voltage AC ($f > 1$ Hz)	V_{GS}	± 30	
Continuous drain current $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	I_D	62 40	A
Pulsed drain current, pulse width limited by T_{jmax}	I_{DM}	192	
MOSFET dv/dt ruggedness $V_{DS} = 0..400\text{V}$	dV/dt	50	V/ns
Operating junction and storage temperature	T_j, T_{stg}	-55... +150	$^\circ\text{C}$

Thermal and Isolation Characteristics

Parameter	Symbol	Max. Value	Units
Characteristics			
Thermal resistance, junction to case	R_{thJC}	0.2	$^\circ\text{C} / \text{W}$
Isolation voltage, RMS (measured between terminals and mounting base, 50-60 Hz, for 1-2 seconds)	V_{iso}	3000	V

ELECTRICAL CHARACTERISTICS, at $T_C = 25^\circ\text{C}$, unless otherwise specified

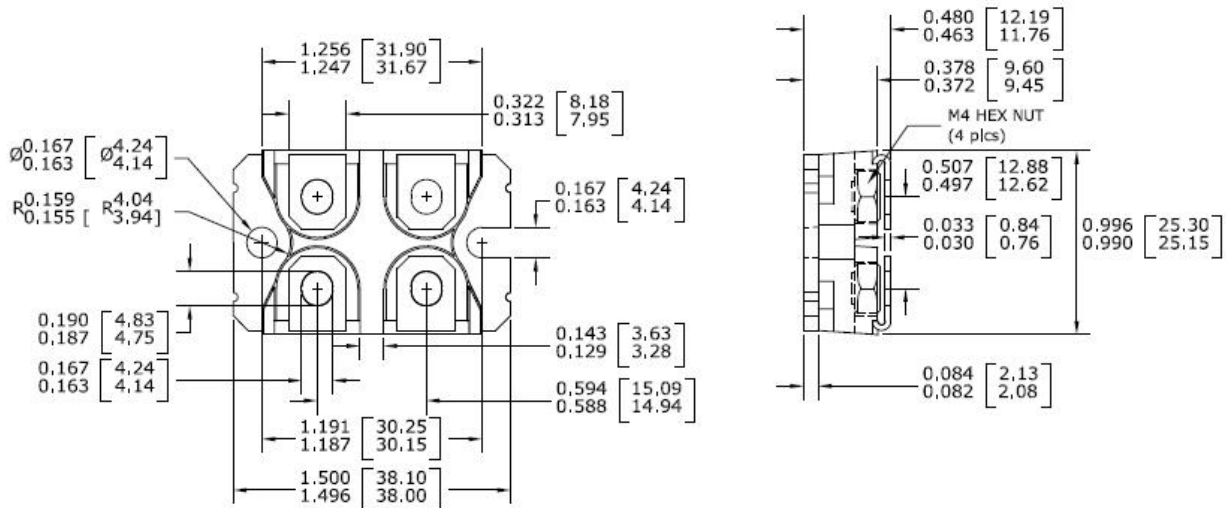
Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{GS} = 0\text{V}, I_D = 500\mu\text{A}$	900	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 5.8\text{mA}$	2.5	3.0	3.5	
Drain-source diode forward voltage	V_{SD}	$V_{GS} = 0\text{V}, I_F = 52\text{A}$	-	0.8	1.2	V
Zero gate voltage drain current	I_{DSS}	$V_{GS} = 0\text{V}, V_{DS} = 900\text{V}$ $T_C = 25^\circ\text{C}$	-	-	20	μA
Gate-source leakage current	I_{GSS}	$V_{GS} = 20\text{V}, V_{DS} = 0\text{V}$	-	-	200	nA
Static drain-source On-resistance	$R_{DS(on)}$	$V_{GS} = 10\text{V}, I_D = 52\text{A}$ $T_C = 25^\circ\text{C}$	-	0.05	0.06	Ω
		$T_C = 150^\circ\text{C}$	-	0.135	-	
Dynamic Characteristics						
Input capacitance	C_{iss}	$V_{DS} = 100\text{V},$ $V_{GS} = 0\text{V},$	-	13600	-	pF
Output capacitance	C_{oss}	$f = 1.0$ MHz	-	660	-	

SWITCHING CHARACTERISTICS, at $T_c = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=400\text{V}$, $I_D=52\text{A}$, $V_{GS}=10\text{V}$, $R_G=3.7\Omega$	-	70	-	ns
Rise time	t_r		-	20	-	
Turn-off delay time	$t_{d(off)}$		-	400	-	
Fall time	t_f		-	25	-	
Gate charge	Q_g	$V_{DD} = 400\text{V}$, $I_D = 52\text{A}$, $V_{GS} = 0 \text{ to } 0\text{V}$	-	540	-	nC
Gate-source charge	Q_{gs}		-	64	-	
Gate-drain charge	Q_{gd}		-	230	-	

Drain-Source Diode Characteristics, at $T_c = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Reverse recovery time	t_{rr}	$V_R = 400\text{V}$, $I_S = I_F = 52\text{A}$	-	920	-	ns
Reverse recovery charge	Q_{rr}	$di_r/dt = 200\text{A}/\mu\text{s}$	-	60	-	μC

PACKAGE OUTLINE DRAWING


CoolMOS™ is a registered trademark of Infineon Technologies AG.

CAUTION: These devices are ESD sensitive. Use proper handling procedure.

Disclaimer

These specifications may not be considered as a guarantee of components characteristics. Components have to be tested depending on intended application as adjustments may be necessary. The use of **iQXPRZ Power Inc.** components in life support appliances and systems are subject to written approval of **iQXPRZ Power Inc.**